

**SINGLE CHANNEL:
DUAL CHANNEL:**

**FOD070L
FOD073L**

FOD270L

ABSOLUTE MAXIMUM RATINGS (No derating required up to 85°C)

Parameter	Symbol	Value	Units
Storage Temperature	T_{STG}	-40 to +125	°C
Operating Temperature	T_{OPR}	-40 to +85	°C
Lead Solder Temperature (Wave solder only. See reflow profile for surface mount devices)	T_{SOL}	260 for 10 sec	°C
EMITTER			
DC/Average Forward Input Current	I_F (avg)	20	mA
Peak Forward Input Current (50% duty cycle, 1 ms P.W.)	I_F (pk)	40	mA
Peak Transient Input Current - ($\leq 1 \mu s$ P.W., 300 pps)	I_F (trans)	1.0	A
Reverse Input Voltage	V_R	5	V
Input Power Dissipation	P_D	35	mW
DETECTOR			
Average Output Current	I_O (avg)	60	mA
Emitter-Base Reverse Voltage (FOD070L, FOD270L)	V_{EB}	0.5	V
Supply Voltage, Output Voltage	V_{CC}, V_O	-0.5 to 7	V
Output power dissipation	P_D	100	mW

ELECTRICAL CHARACTERISTICS ($T_A = 0$ to 70°C Unless otherwise specified)

INDIVIDUAL COMPONENT CHARACTERISTICS

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
EMITTER							
Input Forward Voltage	$T_A = 25^\circ\text{C}$	V_F	All		1.35	1.7	V
	Each Channel ($I_F = 1.6 \text{ mA}$)					1.75	
Input Reverse Breakdown Voltage	($T_A = 25^\circ\text{C}$, $I_R = 10 \mu\text{A}$) Each Channel	BV_R	All	5.0			V
DETECTOR							
Logic high output current	($I_F = 0 \text{ mA}$, $V_O = V_{CC} = 3.3 \text{ V}$)	I_{OH}	FOD070L FOD270L		0.05	25	μA
	Each Channel		FOD073L				
Logic Low Supply Current	$I_F = 1.6 \text{ mA}$, $V_O = \text{Open}$, $V_{CC} = 3.3 \text{ V}$	I_{CCL}	FOD070L FOD270L		0.5	1.5	mA
	$I_{F1} = I_{F2} = 1.6 \text{ mA}$ $V_{O1} = V_{O2} = \text{Open}$, $V_{CC} = 3.3 \text{ V}$		FOD073L		0.8	3	
Logic High Supply Current	$I_F = 0 \text{ mA}$, $V_O = \text{Open}$, $V_{CC} = 3.3 \text{ V}$	I_{CCH}	FOD070L FOD270L		0.01	1	μA
	$I_{F1} = I_{F2} = 0 \text{ mA}$ $V_{O1} = V_{O2} = \text{Open}$, $V_{CC} = 3.3 \text{ V}$		FOD073L		0.01	2	

** All typicals at $T_A = 25^\circ\text{C}$

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TRANSFER CHARACTERISTICS ($T_A = 0$ to 70°C Unless otherwise specified)

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
COUPLED							
Current transfer ratio (Notes 1,2)	$(I_F = 0.5 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 3.3 \text{ V})$	CTR	ALL	400		7000	%
Logic low output voltage output voltage (Note 2)	$(I_F = 1.6 \text{ mA}, I_O = 8 \text{ mA}, V_{CC} = 3.3 \text{ V})$	V_{OL}	ALL		0.07	0.3	V
	$(I_F = 5 \text{ mA}, I_O = 15 \text{ mA}, V_{CC} = 3.3 \text{ V})$		ALL		0.07	0.4	

** All typicals at $T_A = 25^\circ\text{C}$

SWITCHING CHARACTERISTICS ($T_A = 0$ to 70°C unless otherwise specified., $V_{CC} = 3.3 \text{ V}$)

Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Propagation delay time to logic low	$(R_L = 4.7 \text{ k}\Omega, I_F = 0.5 \text{ mA})$ (Note 2) (Fig. 17)	T_{PHL}	FOD070L FOD270L		3	30	μs
			FOD073L		5		
Propagation delay time to logic high	$(R_L = 4.7 \text{ k}\Omega, I_F = 0.5 \text{ mA})$ (Note 2) (Fig. 17)	T_{PLH}	FOD070L FOD270L		50	90	μs
			FOD073L		25		
Common mode transient immunity at logic high	$(I_F = 0 \text{ mA}, V_{CM} = 10 \text{ V}_{P-P})$ $T_A = 25^\circ\text{C}$ ($R_L = 2.2 \text{ k}\Omega$) (Note 3) (Fig. 18)	$ CM_H $	ALL	1,000	10,000		V/ μs
Common mode transient immunity at logic low	$(I_F = 1.6 \text{ mA}, V_{CM} = 10 \text{ V}_{P-P})$ $R_L = 2.2 \text{ k}\Omega$ $T_A = 25^\circ\text{C}$ (Note 3) (Fig. 18)	$ CM_L $	ALL	1,000	10,000		V/ μs

** All typicals at $T_A = 25^\circ\text{C}$

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ISOLATION CHARACTERISTICS ($T_A = 0$ to 70°C Unless otherwise specified)

Characteristics	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Input-output insulation leakage current	(Relative humidity = 45%) ($T_A = 25^\circ\text{C}$, $t = 5$ s) ($V_{I-O} = 3000$ VDC) (Note 4)	I_{I-O}	ALL			1.0	μA
Withstand insulation test voltage	(RH $\leq 50\%$, $T_A = 25^\circ\text{C}$) (Note 4) ($t = 1$ min.)	V_{ISO}	FOD070L FOD073L	2500			V_{RMS}
			FOD270L	5000			
Resistance (input to output)	(Note 4) ($V_{I-O} = 500$ VDC)	R_{I-O}	ALL		10^{12}		Ω
Capacitance (input to output)	(Note 4,5) ($f = 1$ MHz)	C_{I-O}	ALL		0.7		pF
Input-Input Insulation leakage current	(RH $\leq 45\%$, $V_{I-I} = 500$ VDC (Note 6))	I_{I-I}	FOD073L	0.005			μA
Input-Input Resistance	($V_{I-I} = 500$ VDC) (Note 6)	R_{I-I}	FOD073L		10^{11}		Ω
Input-Input Capacitance	($f = 1$ MHz) (Note 6)	C_{I-I}	FOD073L		0.03		pF

** All typicals at $T_A = 25^\circ\text{C}$

NOTES

1. Current Transfer Ratio is defined as a ratio of output collector current, I_O , to the forward LED input current, I_F times 100%.
2. Pin 7 open. (FOD070L and FOD270L only)
3. Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM}/dt on the leading edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0$ V). Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{CM}/dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8$ V).
4. Device is considered a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
5. For dual channel devices, C_{I-O} is measured by shorting pins 1 and 2 or pins 3 and 4 together and pins 5 through 8 shorted together.
6. Measured between pins 1 and 2 shorted together, and pins 3 and 4 shorted together.

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TYPICAL PERFORMANCE CURVES

Fig. 1 Input Forward Current vs Forward Voltage

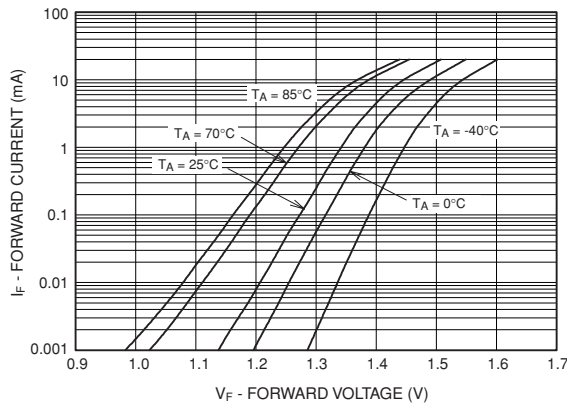


Fig. 2 Current Transfer Ratio vs. Input Forward Current (FOD270L only)

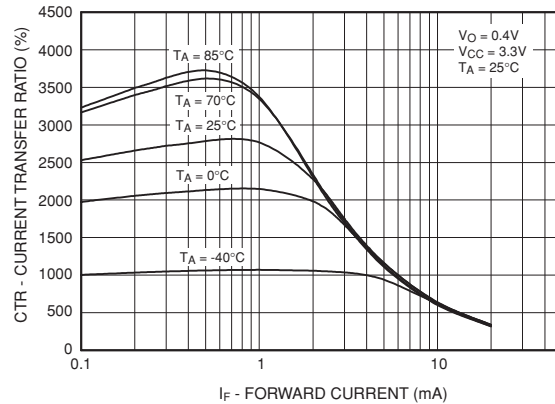


Fig. 3 Current Transfer Ratio vs. Input Forward Current (FOD070L only)

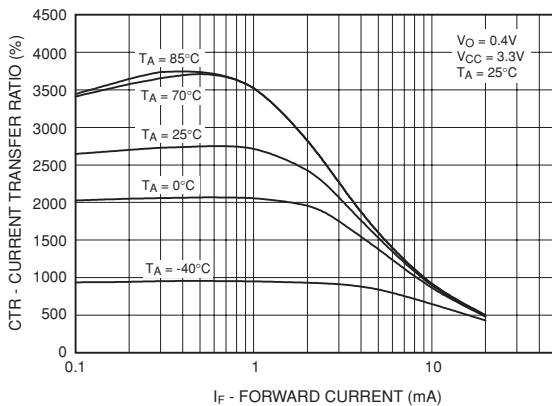


Fig. 4 Current Transfer Ratio vs. Input Forward Current (FOD073L only)

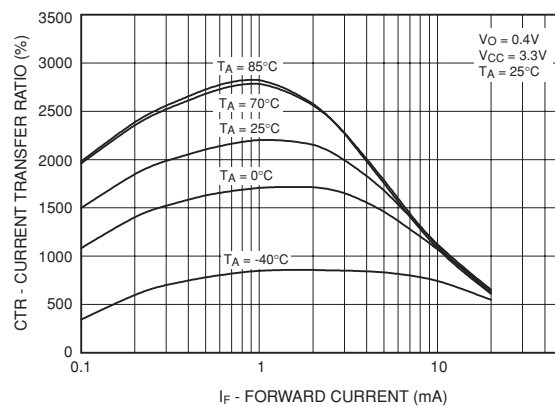


Fig. 5 DC Transfer Characteristics (FOD070L, FOD270L)

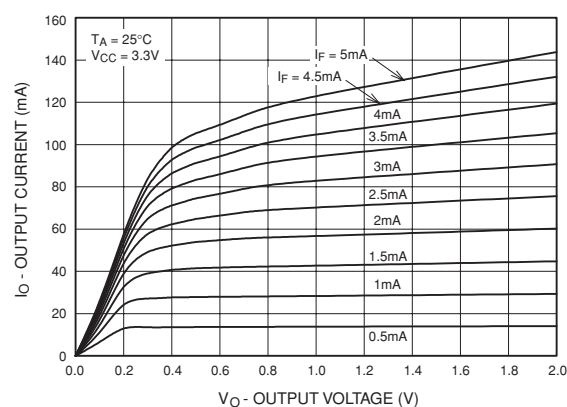
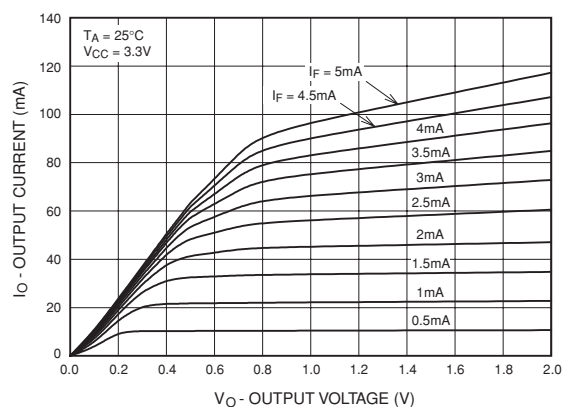


Fig. 6 DC Transfer Characteristics (FOD073L only)



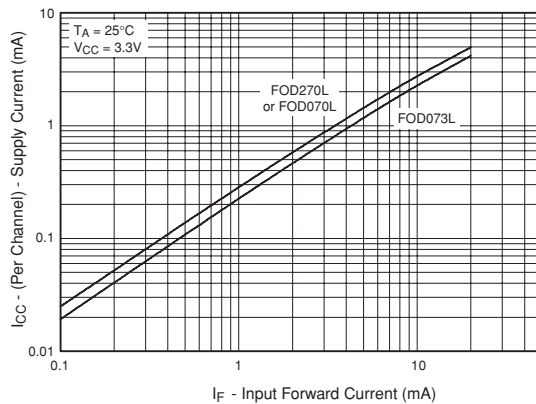
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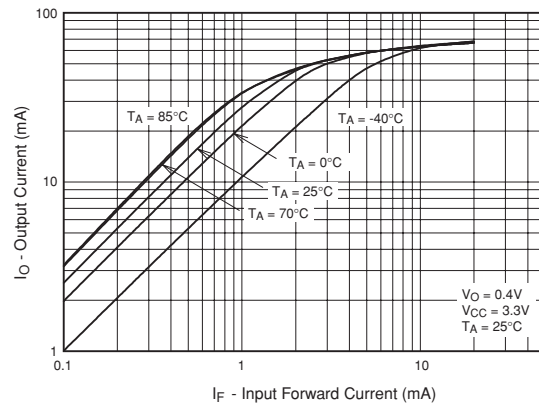
FOD270L

TYPICAL PERFORMANCE CURVES

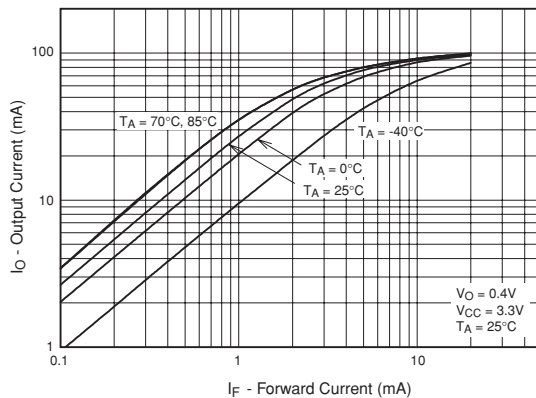
**Fig. 7 Supply Current vs Input Forward Current
(FOD270L, FOD070L, FOD073L)**



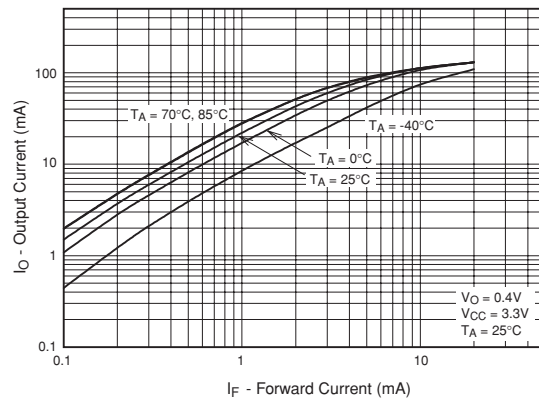
**Fig. 8 Output Current vs Input Forward Current
(FOD270L only)**



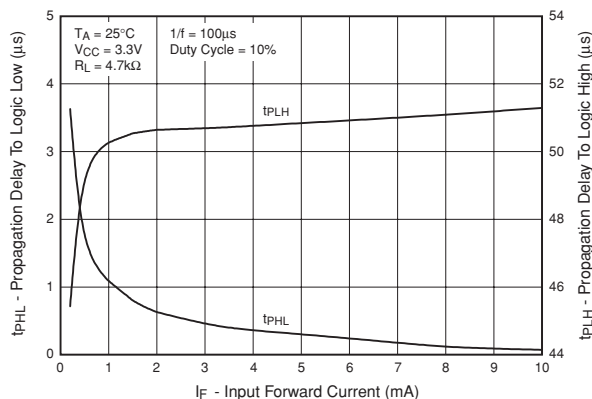
**Fig. 9 Output Current vs Input Forward Current
(FOD070L only)**



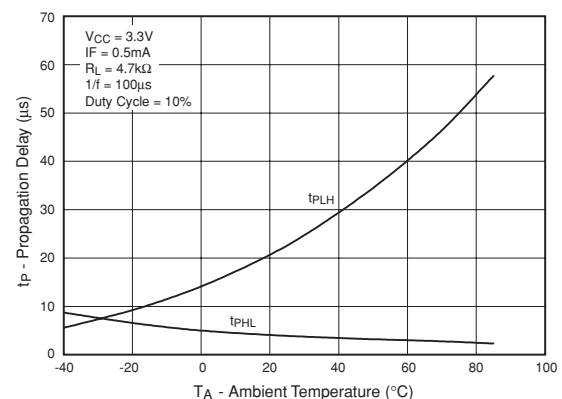
**Fig. 10 Output Current vs Input Forward Current
(FOD073L only)**



**Fig. 11 Propagation Delay vs.
Input Forward Current (FOD070L only)**



**Fig. 12 Propagation Delay vs.
Ambient Temperature (FOD073L only)**



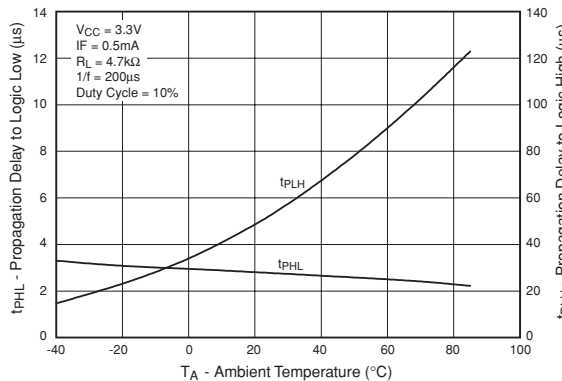
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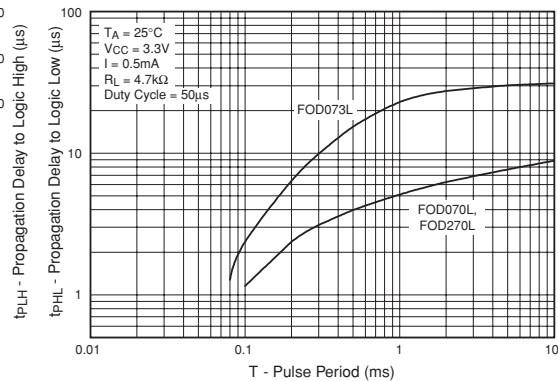
FOD270L

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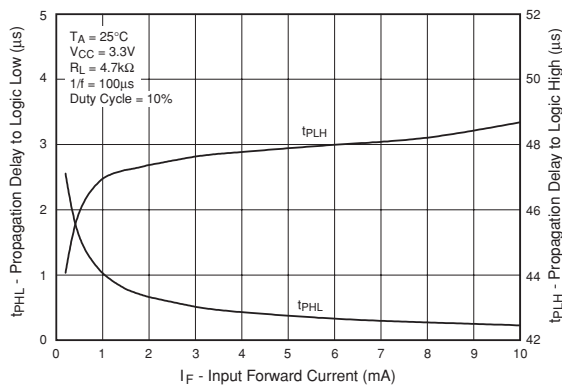
**Fig. 13 Propagation Delay vs.
Ambient Temperature (FOD070L, FOD270L)**



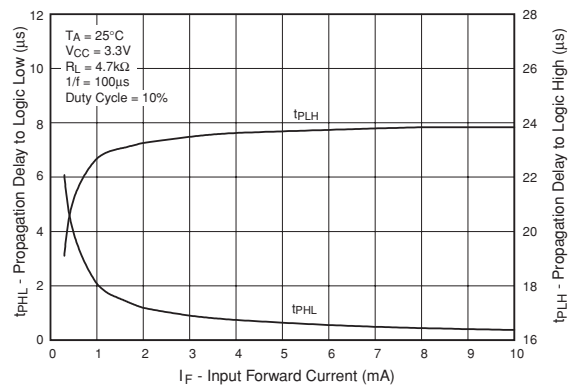
**Fig. 14 Propagation Delay To Logic Low vs Pulse Period
(FOD073L, FOD070L, FOD270L)**



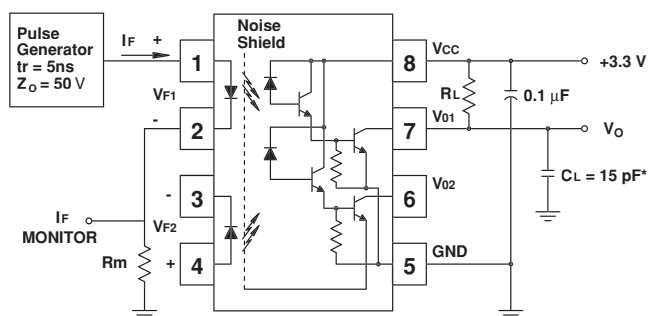
**Fig. 15 Propagation Delay vs.
Input Forward Current (FOD270L only)**



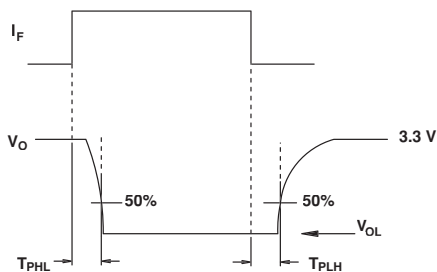
**Fig. 16 Propagation Delay vs.
Input Forward Current (FOD073L only)**



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Test Circuit for FOD073L



*Includes Probe and Fixture Capacitance

Fig. 17 Switching Time Test Circuit

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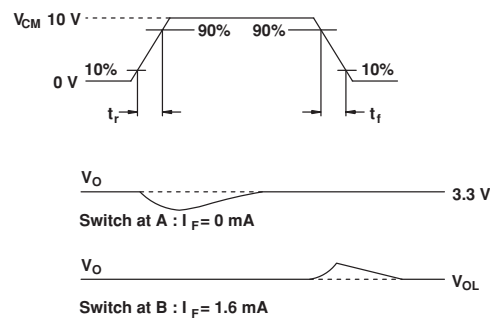
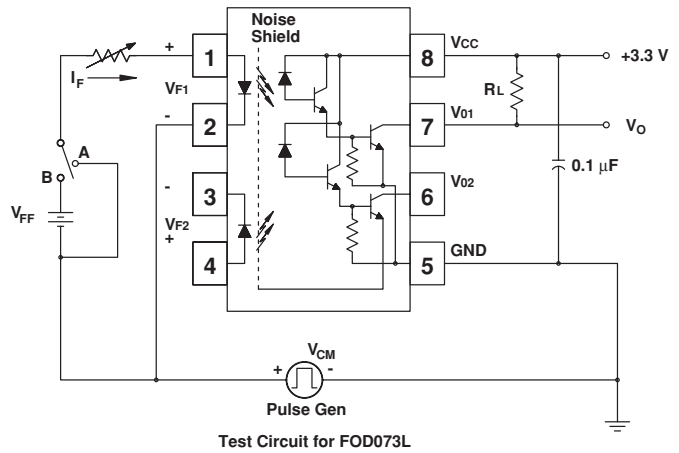
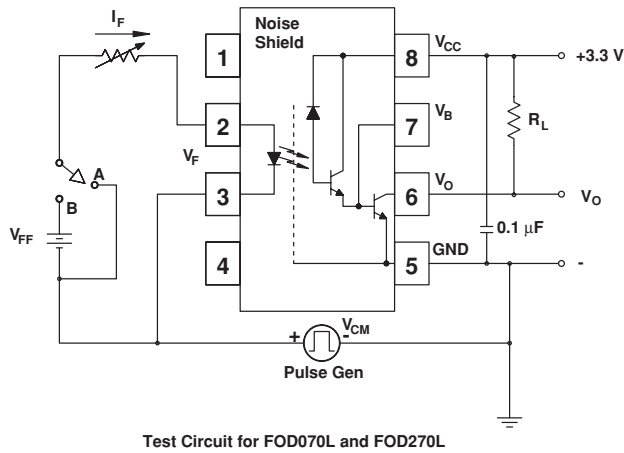


Fig. 18 Common Mode Immunity Test Circuit

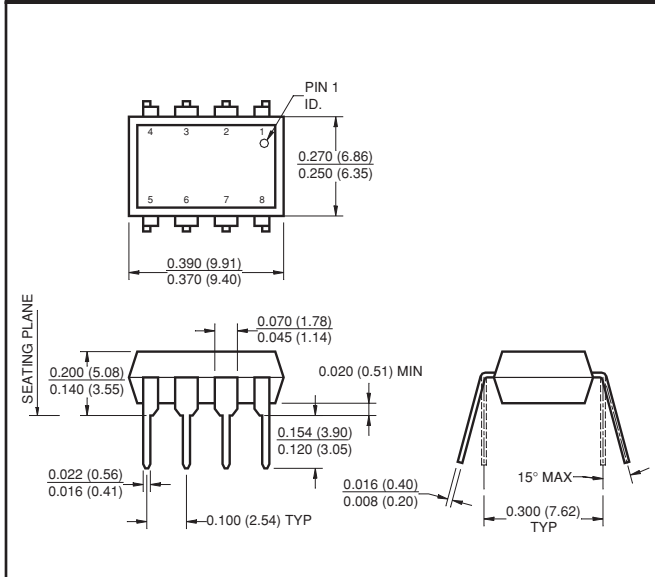
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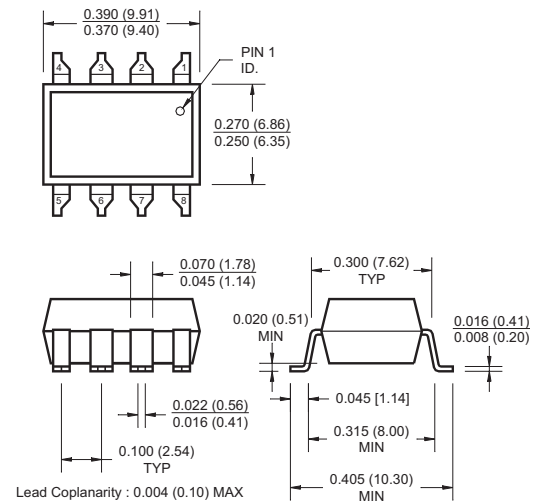
FOD270L

8-Pin DIP

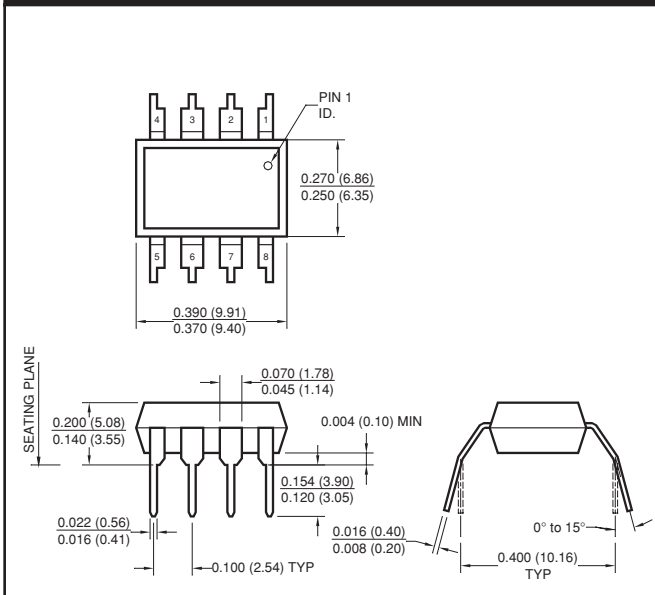
Package Dimensions (Through Hole)



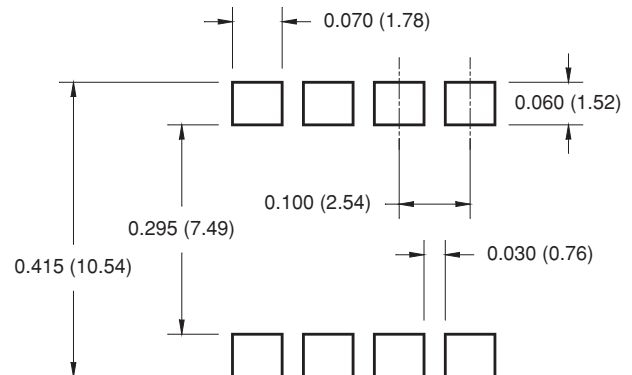
Package Dimensions (Surface Mount)



Package Dimensions (0.4"Lead Spacing)



**Recommend Pad Layout for
Surface Mount Leadform**



NOTE

All dimensions are in inches (millimeters)

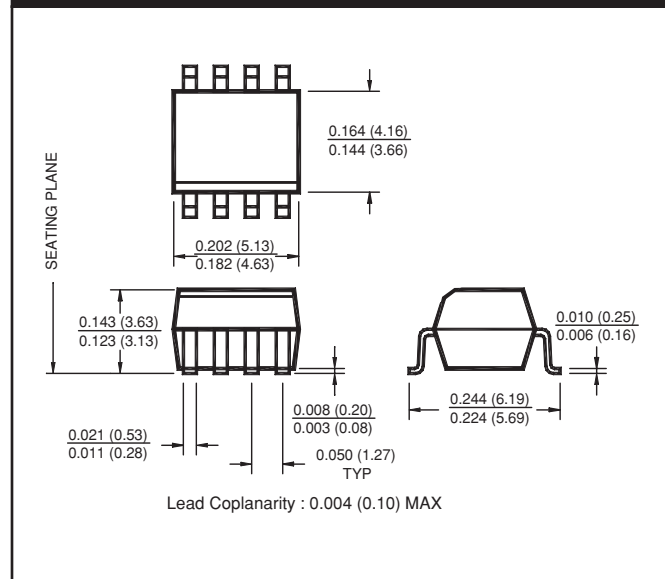
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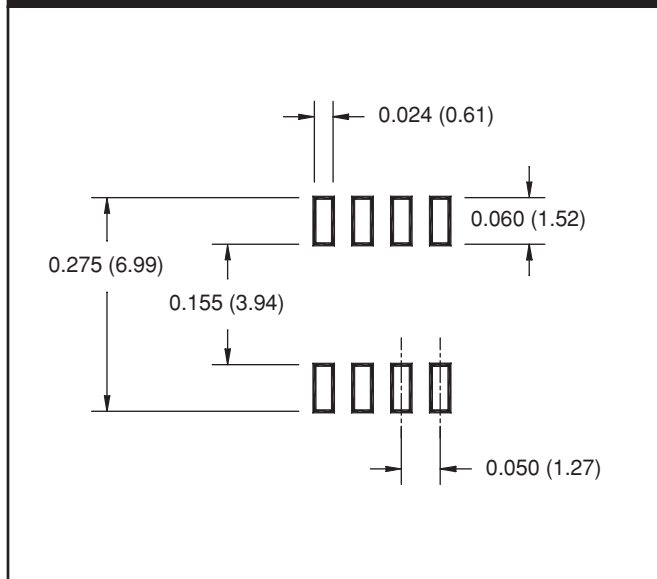
FOD270L

SOIC 8

Package Dimensions (Surface Mount)



Recommend Pad Layout



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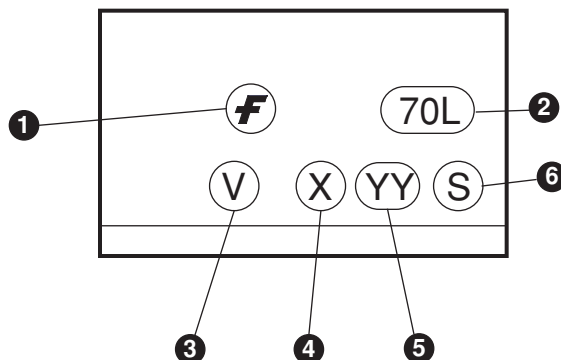
**FOD070L
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ORDERING INFORMATION

Option	Order Entry Identifier	Description
S	FOD270LS	Surface Mount Lead Bend (DIP Package Only)
SD	FOD270LSD	Surface Mount; Tape and reel (DIP Package Only) (1000 units per reel)
SV	Pending approval	Surface Mount; VDE 0884 (DIP Package Only)
SDV	Pending approval	Surface Mount; Tape and reel (DIP Package Only); VDE 0884 (1000 units per reel)
T	FOD270LT	0.4" lead spacing (DIP Package Only)
TV	Pending approval	0.4" lead spacing, VDE 0884 (DIP Package Only)
R1	FOD070LR1	Tape and reel (500 units per reel) (SOIC 8 Package only)
R1V	Pending approval	VDE, Tape and reel (500 units per reel) (SOIC 8 Package only)
R2	FOD070LR2	Tape and reel (2500 units per reel) (SOIC 8 Package only)
R2V	Pending approval	VDE 0884, Tape and reel (2500 units per reel) (SOIC 8 Package only)
V	Pending approval	VDE 0884

MARKING INFORMATION (FOD070L, FOD073L)



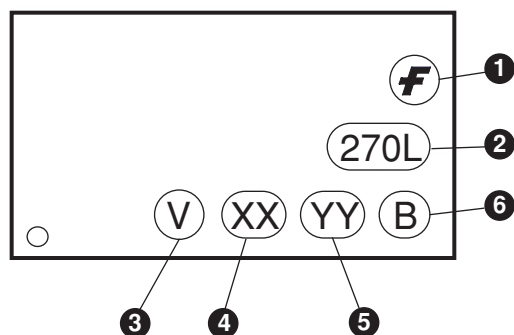
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

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MARKING INFORMATION (FOD270L)



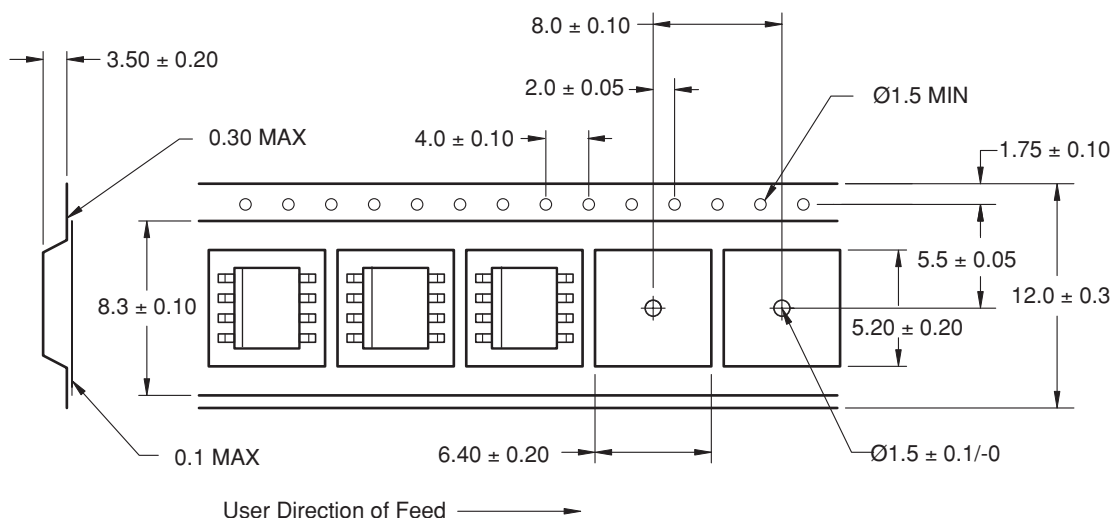
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., '03'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

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Carrier Tape Specifications (FOD070L and FOD073L)

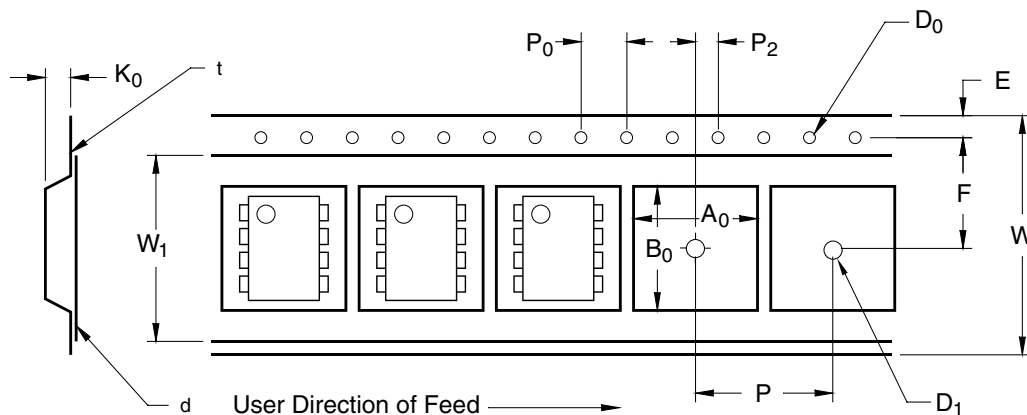


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Carrier Tape Specifications (FOD270L)



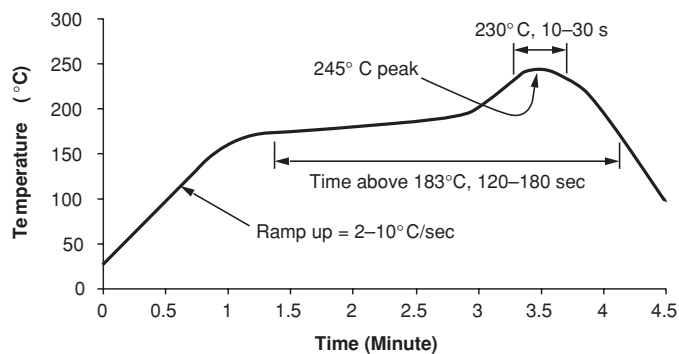
Description	Symbol	Dimension in mm
Tape Width	W	16.0 ± 0.3
Tape Thickness	t	0.30 ± 0.05
Sprocket Hole Pitch	P_0	4.0 ± 0.1
Sprocket Hole Diameter	D_0	1.55 ± 0.05
Sprocket Hole Location	E	1.75 ± 0.10
Pocket Location	F	7.5 ± 0.1
Pocket Pitch	P_2	4.0 ± 0.1
Pocket Dimensions	A_0	10.30 ± 0.20
	B_0	10.30 ± 0.20
	K_0	4.90 ± 0.20
Cover Tape Width	W_1	1.6 ± 0.1
Cover Tape Thickness	d	0.1 max
Max. Component Rotation or Tilt		10°
Min. Bending Radius	R	30

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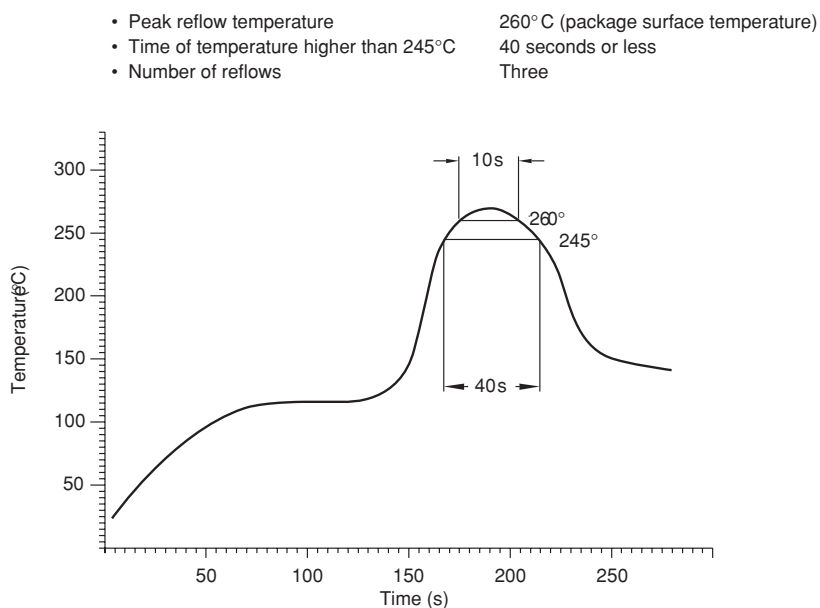
FOD270L

Reflow Profile (FOD070L and FOD073L)



- Peak reflow temperature: 245°C (package surface temperature)
- Time of temperature higher than 183°C for 120-180 seconds
- One time soldering reflow is recommended

Reflow Profile (FOD270L)



- Peak reflow temperature 260° C (package surface temperature)
- Time of temperature higher than 245°C 40 seconds or less
- Number of reflows Three

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.